








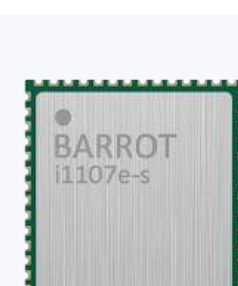


# BARROT Automotive Bluetooth SOC Solution

图片 Picture	模组型号 Module Series	硬件架构 Hardware architecture	硬件特性 Hardware									软件特性 Software						
			主芯片 Chip	尺寸 Dimension(l*w*h)	操作温度 Operation Temperature	工作电压 Operating voltage(V)	蓝牙语音数据接口 Bluetooth voice	蓝牙音乐数据接口 Bluetooth A2DP stream	支持Mic数目 number of mic	ROHS/ REACH Compliant	天线接口 Antenna interface	蓝牙版本 Bluetooth Spec	设备多连接 MultiConnect	支持的操作系统 Support OperateSystem	降噪/消回声 NoiseReducte/ EchoCancel	蓝牙音乐编解码格式 audiodata over ACL	支持语音格式 voice over (e)SCO	BQB 认证 BQB Certification
	i2224e-s	SoC (硬件集成了蓝牙协议栈的软件实现, 不占用系统资源, 开发难度低)	CSR1024	13.7mm*16.6mm*2.7mm	-40°C to +85°C	VBAT: 3.0V to 3.6V VDDIO:3.3V	No	No	No	Yes	External: PCB/SMT	IC BQB: Bluetooth5.0 BLE Module BQB: Bluetooth4.0	No	Full Support	No	No	No	Yes
	i1553e-s	SoC (硬件集成了蓝牙协议栈的软件实现, 不占用系统资源, 开发难度低)	BR8051A01	21.3mm*13.7mm*2.5mm	-40°C to +85°C	VBAT: 3.0V to 3.6V VDDIO:3.3V	PCM/IIS	PCM/IIS	No	Yes	External: PCB/SMT/IPEX	IC BQB: Bluetooth5.0 Module BQB: Bluetooth5.0	Yes	Full Support	1)Software algorithm(Integrated to the linux/android system) Barrot软件算法集成 2)External Hardware DSP 硬件DSP方式	SBC	NBS(8K窄带语音)/ WBS (16K宽带语音)	Yes
	i1636e-s	SoC (硬件集成了蓝牙协议栈的软件实现, 不占用系统资源, 开发难度低)	KW38	13.7mm*16.6mm*2.5mm	-40°C to +85°C	VBAT:3.3V VDDIO:3.3V	No	No	No	Yes	External: PCB/SMT	IC BQB: Bluetooth5.0 Module BQB:-	No	Full Support	No	No	No	Yes
	i480e	SoC (硬件集成了蓝牙协议栈的软件实现, 不占用系统资源, 开发难度低)	CSR8670	21.3mm*13.7mm*1.7mm	-40°C to +85°C	VBAT: 2.5V to 4.25V VDDIO:1.8V	PCM/IIS/ Analog output	Analog output/ IIS	双mic	Yes	External: PCB/SMT/IPEX	IC BQB: Bluetooth5.1 Module BQB: Bluetooth5.0	Yes	Full Support	Qualcomm cVc 8th	SBC/AAC/APT-x ll	NBS(8K窄带语音)/ WBS (16K宽带语音)	Yes
	i1121e-s	SoC (硬件集成了蓝牙协议栈的软件实现, 不占用系统资源, 开发难度低)	QCC3021	19.8mm*14.8mm*3.2mm	-40°C to +85°C	VBAT: 3.0V to 3.6V VDDIO:3.3V	PCM/ Analog output/ USB	Analog output/ IIS/USB	单mic	Yes	External: PCB/SMT/IPEX	IC BQB: Bluetooth5.1 Module BQB: Bluetooth5.1	Yes	Android(latest)/ Linux/QNX/ RTOS	Qualcomm cVc 8th	SBC/AAC	NBS(8K窄带语音)/ WBS (16K宽带语音)	Yes
	i1663e	SoC (硬件集成了蓝牙协议栈的软件实现, 不占用系统资源, 开发难度低)	RTL8762CMF-CG	25.2mm*15.2mm*3.2mm	-40°C to +85°C	VBAT: 3.0V to 3.6V VDDIO:3.3V	No	No	No	Yes	External: PCB/SMT	IC BQB: Bluetooth5.4 BLE Module BQB:-	No	Full Support	No	No	No	Yes
	i1556e-s	SoC (硬件集成了蓝牙协议栈的软件实现, 不占用系统资源, 开发难度低)	QCC3056	21.3mm*13.7mm*2.5mm	-40°C to +85°C	VBAT: 3.0V to 3.6V VDDIO:3.3V	PCM(in)/IIS(in)/ Analog output/ USB	Analog output/ IIS(in)/PCM(in)/USB	双mic	Yes	External: PCB/SMT/IPEX	IC BQB: Bluetooth5.3 Module BQB: Bluetooth5.3	Yes	Full Support	1)Software algorithm(Integrated to the linux/android system) Barrot软件算法集成 2)External Hardware DSP 硬件DSP方式	SBC/AAC/aptx /aptx-hd	NBS(8K窄带语音)/ WBS (16K宽带语音)	Planning
	i1662e-s	SoC (硬件集成了蓝牙协议栈的软件实现, 不占用系统资源, 开发难度低)	RTL8762CMF-CG	16.6mm*13.7mm*2.5mm	-40-85°C	VBAT: 3.0V to 3.6V	No	No	No	Yes	External: PCB/SMT	IC BQB: Bluetooth5.4 BLE Module BQB: Bluetooth5.3	No	Full Support	No	No	No	Yes
	i1676e	SoC (硬件集成了蓝牙协议栈的软件实现, 不占用系统资源, 开发难度低)	RTL8762CMF-CG	30mm*25mm*3mm	-40°C to +85°C	VBAT: 3.0V to 3.6V	No	No	No	Yes	External: PCB/SMT	IC BQB: Bluetooth5.4 BLE Module BQB:-	No	Full Support	No	No	No	Yes
	i1107e-s	SoC (硬件集成了蓝牙协议栈的软件实现, 不占用系统资源, 开发难度低)	QCC3007	19.8mm*14.8mm*2.3mm	-40°C to +85°C	VBAT: 3.0V to 3.6V VDDIO:3.3V	PCM/IIS/ Analog output	Analog output /IIS	单mic	Yes	External: PCB/SMT/IPEX	IC BQB: Bluetooth5.0 Module BQB: Bluetooth5.0	Yes	Android(latest)/ Linux/QNX/ RTOS	Qualcomm cVc 8th	SBC/AAC	NBS(8K窄带语音)/ WBS (16K宽带语音)	Yes

\* Barrot 蓝牙协议栈支持的Profiles: BR/EDR:SPP,HFP,HSP,PBAP,MAP,A2DP,AVRCP,HID,DUN,PAN,FTP,OPP BLE:GATT,ANCS等